

L Number	Hits	Search Text	DB	Time stamp
1	6	5323060.pn. 6337226.pn. 6337227.pn. 6340846.pn. 6492726.pn. 20020030257.pn.	USPAT; US-PGPUB	2004/03/03 10:26
2	4672	257/686.ccls. 257/697.ccls. 257/723.ccls. 257/725.ccls. 257/777.ccls. 257/784.ccls. 257/789.ccls. 257/795.ccls. 438/109.ccls.	USPAT; US-PGPUB	2004/03/03 10:30
3	25497	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)	USPAT; US-PGPUB	2004/03/03 11:30
4	864	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))	USPAT; US-PGPUB	2004/03/03 11:31
5	832	(257/686.ccls. 257/697.ccls. 257/723.ccls. 257/725.ccls. 257/777.ccls. 257/784.ccls. 257/789.ccls. 257/795.ccls. 438/109.ccls.) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))	USPAT; US-PGPUB	2004/03/03 10:38
6	693	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and (encapsula\$7 adhesive tape "silver-filled")	USPAT; US-PGPUB	2004/03/03 11:31
7	474	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and (encapsula\$7 adhesive tape "silver-filled")) and (wire near bond\$6)	USPAT; US-PGPUB	2004/03/03 11:32
9	288	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) same ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))	USPAT; US-PGPUB	2004/03/03 11:23
12	29204	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))	USPAT; US-PGPUB	2004/03/03 11:25
13	5065	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (encapsula\$7 adhesive tape "silver-filled")	USPAT; US-PGPUB	2004/03/03 11:25
14	1331	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (encapsula\$7 adhesive tape "silver-filled")) same (wire near bond\$6)	USPAT; US-PGPUB	2004/03/03 11:26
15	321	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and ((encapsula\$7 adhesive tape "silver-filled") same (wire near bond\$6))	USPAT; US-PGPUB	2004/03/03 11:33
16	371	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) same ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (encapsula\$7 adhesive tape "silver-filled")) ((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) same ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (wire near bond\$6)) ((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and ((encapsula\$7 adhesive tape "silver-filled") same (wire near bond\$6)))	USPAT; US-PGPUB	2004/03/03 11:29

17	256	(((((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and ((encapsula\$7 adhesive tape "silver-filled") same (wire near bond\$6))) not ((((((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) same ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (encapsula\$7 adhesive tape "silver-filled")) ((((((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) same ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (wire near bond\$6)))	USPAT; US-PGPUB	2004/03/03 11:29
18	20686	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)	EPO; JPO; DERWENT; IBM_TDB	2004/03/03 11:30
20	22348	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))	EPO; JPO; DERWENT; IBM_TDB	2004/03/03 11:31
21	2644	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and (encapsula\$7 adhesive tape "silver-filled")	EPO; JPO; DERWENT; IBM_TDB	2004/03/03 11:31
22	336	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and (encapsula\$7 adhesive tape "silver-filled")) and (wire near bond\$6)	EPO; JPO; DERWENT; IBM_TDB	2004/03/03 11:32
23	0	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and ((encapsula\$7 adhesive tape "silver-filled") same (wire near bond\$6))	EPO; JPO; DERWENT; IBM_TDB	2004/03/03 11:33
24	266	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and ((encapsula\$7 adhesive tape "silver-filled") same (wire near bond\$6))	EPO; JPO; DERWENT; IBM_TDB	2004/03/03 11:33
8	264	(257/686.ccls. 257/697.ccls. 257/723.ccls. 257/725.ccls. 257/777.ccls. 257/784.ccls. 257/789.ccls. 257/795.ccls. 438/109.ccls.) and ((((((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) and (encapsula\$7 adhesive tape "silver-filled")) and (wire near bond\$6))	USPAT; US-PGPUB	2004/03/03 11:37
10	58	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) same ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (encapsula\$7 adhesive tape "silver-filled")	USPAT; US-PGPUB	2004/03/03 14:36
11	97	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) same ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))) same (wire near bond\$6)	USPAT; US-PGPUB	2004/03/03 14:54
19	87	((package wir\$6) near substrate) mcm (multichip adj module) (chip adj carrier)) and ("chip on chip" "chip-on-chip" "chip-over-chip" "chip over chip" coc (chip near stack\$5))	EPO; JPO; DERWENT; IBM_TDB	2004/03/03 16:34
25	2	jp-11204720-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/03/03 16:35